

CLAIM AMENDMENTS

1. (Currently Amended) A semiconductor device, comprising:
a conductive layer;
a first contact comprising a ball on said ~~first~~ conductive layer;
a first bonding pad spaced apart from said conductive layer;
~~a second contact on said first bonding pad;~~ and
a bonding wire electrically connecting said first contact to said first bonding pad and
forming a second contact, wherein said second contact ~~includes~~ including at least two layers
of said bonding wire, lying directly on each other, so that said bonding wire includes at least
one reverse bend, and one of the layers is in contact with said first bonding pad.

2 and 3 (Previously Cancelled)

4. (Previously Amended) The semiconductor device according to claim 1, wherein
said conductive layer includes an inner lead.

5. (Previously Amended) The semiconductor device according to claim 1,
comprising a base;
a semiconductor element on said base with a die pad interposed between said
semiconductor element and said base;
a sealing resin sealing said semiconductor element; and
an external terminal on a rear surface of said base, wherein
said conductive layer includes a land on said base, and
said first bonding pad is on said semiconductor element.

6. (Previously Amended) The semiconductor device according to claim 1,
comprising:
a base;
first and second semiconductor elements mounted on said base with a die pad
interposed between said base and said first and second semiconductor elements;
a sealing resin sealing said first and second semiconductor elements; and
an external terminal on a rear surface of said base, wherein
said conductive layer includes a second bonding pad on said first
semiconductor element, and
said first bonding pad is on said second semiconductor element.

7. (Currently Amended) A method of manufacturing a semiconductor device, comprising, sequentially:

joining a ball ~~formed~~ at a tip end of a bonding wire to a conductive layer as a first contact;

joining a first part of said bonding wire directly to a bonding pad;

mechanically deforming a second part of said bonding wire, while said first part of said bonding wire is joined to said bonding pad, so that said second part of said bonding wire, is folded onto said first part of said bonding wire, directly opposite said bonding pad with said first part of said bonding wire between said bonding pad and said second part of said bonding wire; and

joining said second part of said bonding wire to said first part of said bonding wire while said first part of said bonding wire is on said bonding pad.

8 and 9 (Previously Cancelled)

10. (Previously Amended) The method of manufacturing a semiconductor device according to claim 7, wherein

said bonding wire is held by a bonding tool; and

mechanically deforming said bonding wire includes mechanically deforming said bonding wire on said bonding pad by moving said bonding tool with said bonding wire joined to said bonding pad.